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File: JPAB

Jan 8, 1993

PUB-NO: JP405002777A

DOCUMENT-IDENTIFIER: JP 05002777 A

TITLE: RESIST COATING METHOD

PUBN-DATE: January 8, 1993

INVENTOR-INFORMATION:

NAME

COUNTRY

MIYASHITA, MASATOSHI

ASSIGNEE-INFORMATION:

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N/A

APPL-NO: JP03154588

APPL-DATE: June 26, 1991

US-CL-CURRENT: 118/52

INT-CL (IPC): G11B 7/26; B05D 1/40; B29C 33/38

ABSTRACT:

PURPOSE: To obtain an always specified film thickness by sensing the temp. and humidity in a chamber under coating, the temp. of a glass master disk, the temp. of a resist, and the fluctuation in the evaporation rate of a thinner and controlling the rotating speed of a coater.

CONSTITUTION: Fig. illustrates the embodiment in which the coating at 1140 \AA ; film thickness is executed in an atmosphere where the environmental temp. is not controlled. The temp. and the evaporation rate of the thinner are kept constant and the temps. of the glass master disk, the inside of the chamber and the resist are monitored by temp. sensors 5 to 7. The optimum rotating speed of the coater for obtaining 1140 \AA ; film thickness is determined by a computer from the respective temps. and the rotating speed of the coater is so controlled as to attain this rotating speed. The fluctuation in the film thickness is decreased down to about $\pm 1\%$ in this way and the yield is increased up to 98%.

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